

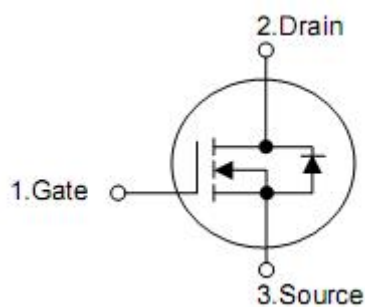
## 1. Description

The KND3404C is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The KND3404C meet the RoHs and Green Product requirement 100% EAS Guaranteed with full function reliability approved.

## 2. Features

- n  $R_{DS(ON),typ.}=5.0m\Omega@V_{GS}=10V$
- n Super low gate charge
- n 100% EAS Guaranteed
- n Green device available
- n Excellent Cdv/dt effect decline
- n Advanced high cell density trench technology

## 3. Symbol



Pin TO-252	Pin DFN5*6	Function
1	4	Gate
2	5,6,7,8	Drain
3	1,2,3	Source

## 4. Ordering Information

Part Number	Package	Brand
KND3404C	TO-252	KIA
KNY3404C	DFN5*6	KIA

## 5. Absolute maximum ratings

( $T_A=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-source voltage	$V_{DS}$	40	V
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Continuous drain current $V_{GS}@10V^1$	$T_C=25^{\circ}\text{C}$	$I_D$	80
	$T_C=100^{\circ}\text{C}$	$I_D$	58
Pulsed drain current <sup>2</sup>	$I_{DM}$	150	A
Single pulse avalanche energy <sup>3</sup>	EAS	110	mJ
Avalanche current	$I_{AS}$	47	A
Total power dissipation <sup>4</sup>	$T_C=25^{\circ}\text{C}$	$P_D$	52.1
Junction and storage temperature range	$T_J, T_{STG}$	-55 to 150	$^{\circ}\text{C}$

## 6. Thermal Data

Parameter	Symbol	Ratings	Units
Thermal resistance, junction-ambient	$R_{thJA}$	62	$^{\circ}\text{C}/\text{W}$
Thermal resistance, Junction-case	$R_{thJC}$	2.4	$^{\circ}\text{C}/\text{W}$

## 7. Electrical characteristics

( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	40	--	--	V
BVDSS Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^{\circ}\text{C}$ , $I_D=1\text{mA}$	--	0.034	--	$V/^{\circ}\text{C}$
Static Drain-Source On-Resistance <sup>2</sup>	$R_{DS(ON)}$	TO-252 $V_{GS}=10V, I_D=15A$ DFN5*6 $V_{GS}=10V, I_D=10A$	--	5.0	6.5	$\text{m}\Omega$
		TO-252 $V_{GS}=4.5V, I_D=12A$ DFN5*6 $V_{GS}=4.5V, I_D=5A$	--	6.5	9	$\text{m}\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.0	--	2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	--	-5.84	--	$\text{mV}/^{\circ}\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=32V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	--	---	1	$\mu A$
		$V_{DS}=32V, V_{GS}=0V, T_J=55^{\circ}\text{C}$	--	---	5	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	--	---	$\pm 100$	nA
Forward Transconductance	$g_{fs}$	$V_{DS}=5V, I_D=15A$	--	25	---	S
Gate Resistance	$R_g$	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	--	1.5	---	$\Omega$
Total Gate Charge (4.5V)	$Q_g$	$V_{DS}=20V, V_{GS}=4.5V, I_D=12A$	--	28	---	nC
Gate-Source Charge	$Q_{gs}$		--	7.8	---	nC
Gate-Drain Charge	$Q_{gd}$		--	12.5	---	nC
Turn-On Delay Time	$T_{d(on)}$	$V_{DD}=15V, V_{GS}=10V, R_G=3.3\Omega, I_D=1A$	--	20	---	ns
Rise Time	$T_r$		--	11.5	---	ns
Turn-Off Delay Time	$T_{d(off)}$		--	84	---	ns
Fall Time	$T_f$		--	8.5	---	ns
Input Capacitance	$C_{iss}$	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	--	3330	---	pF
Output Capacitance	$C_{oss}$		--	270	---	pF
Reverse Transfer Capacitance	$C_{rss}$		--	200	---	pF
<b>Diode Characteristics</b>						
Continuous Source Current <sup>1,5</sup>	$I_S$	$V_G=V_D=0V, \text{Force Current}$	--	--	80	A
Pulsed Source Current <sup>2,5</sup>	$I_{SM}$		--	--	150	A
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	$V_{GS}=0V, I_S=1A, T_J=25^{\circ}\text{C}$	--	--	1	V

Note:1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.

2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .

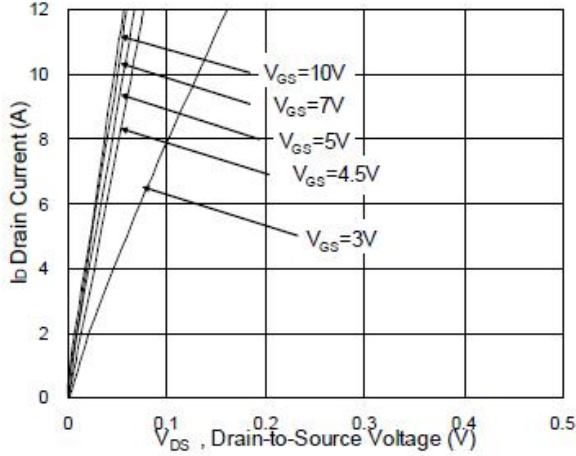
3. The EAS data shows Max.rating. The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=47A$ .

4. The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature.

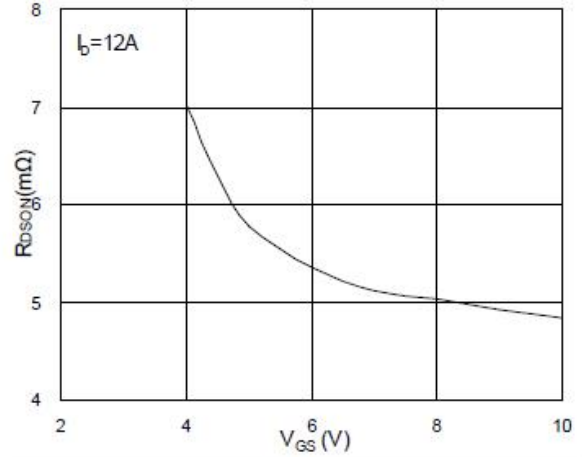
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation

**8. Test circuits**

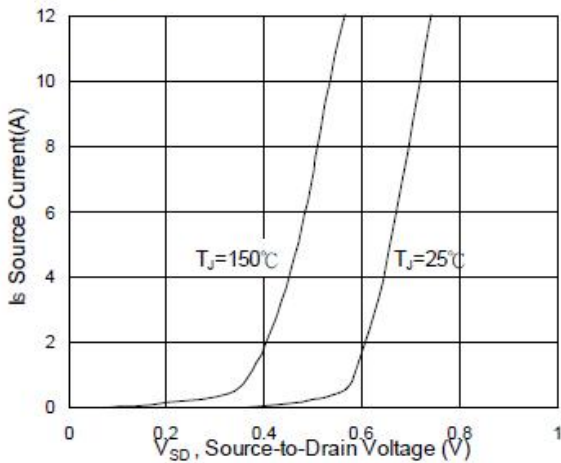
**Typical Characteristics**



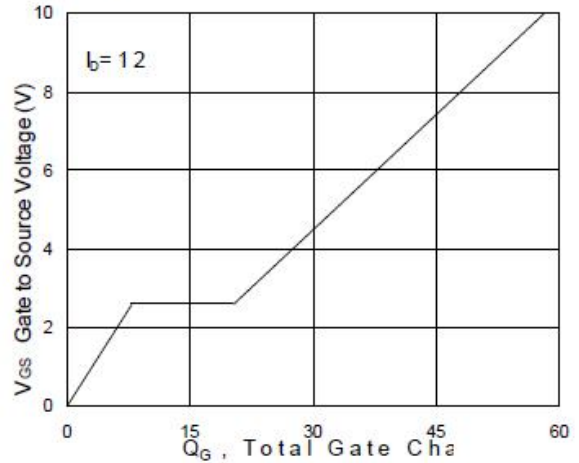
**Fig.1 Typical Output Characteristics**



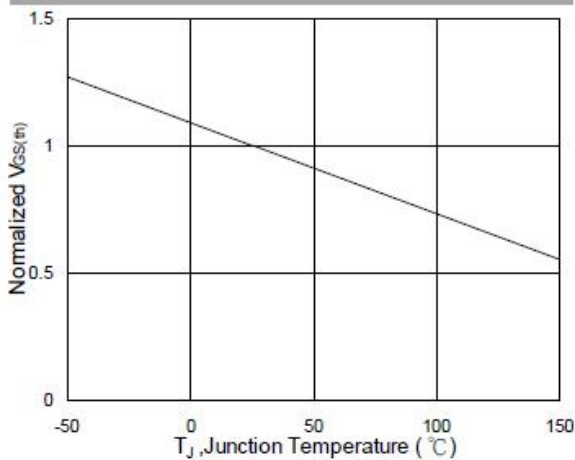
**Fig.2 On-Resistance vs. G-S Voltage**



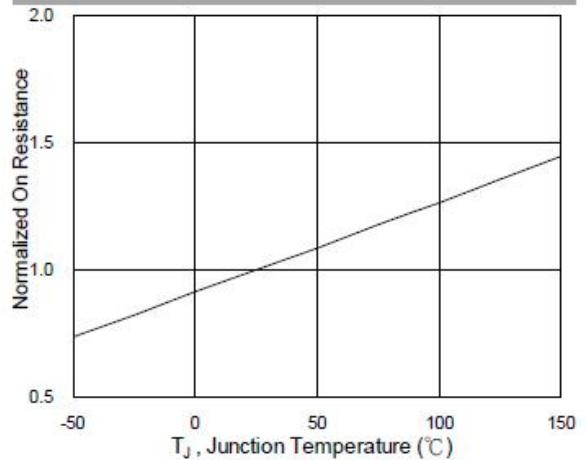
**Fig.3 Forward Characteristics Of Reverse**



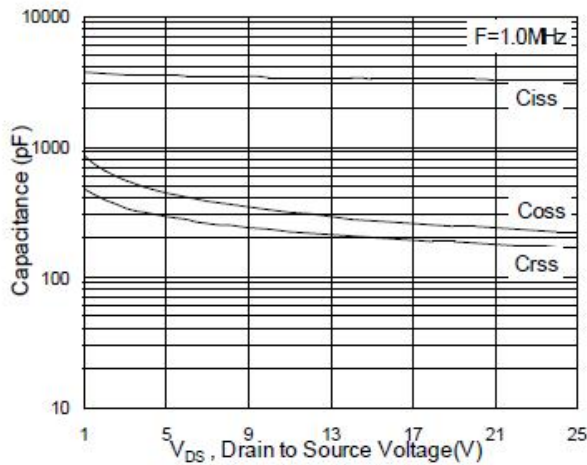
**Fig.4 Gate-Charge Characteristics**



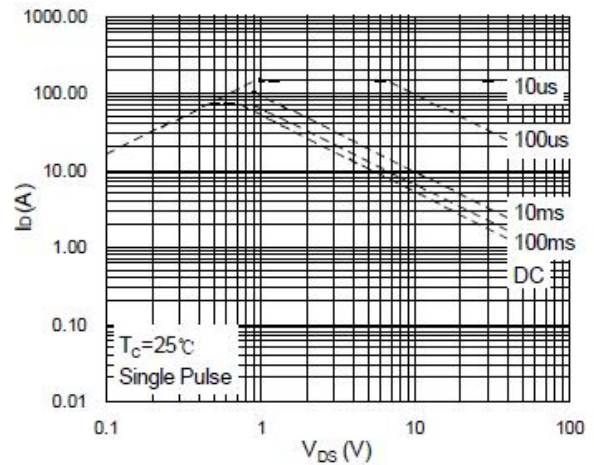
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



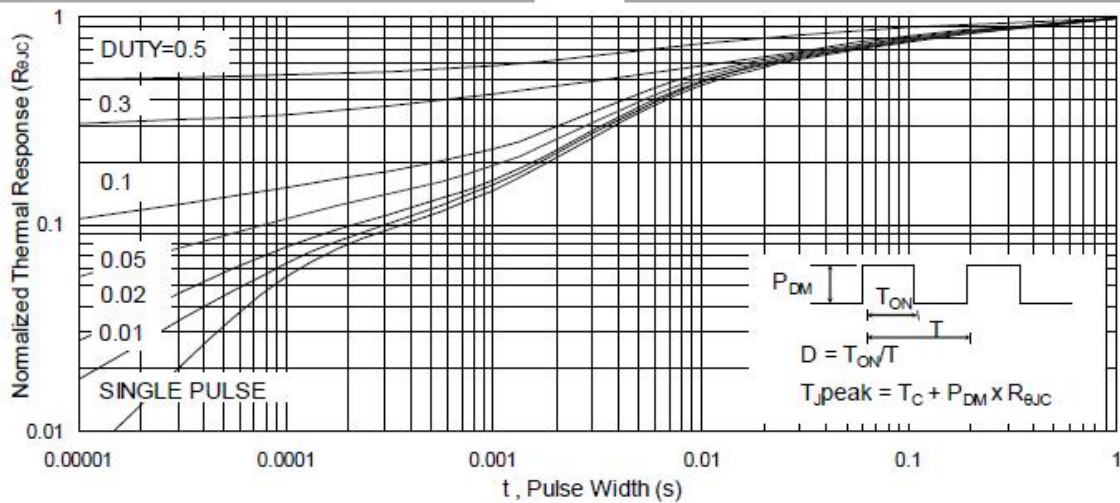
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



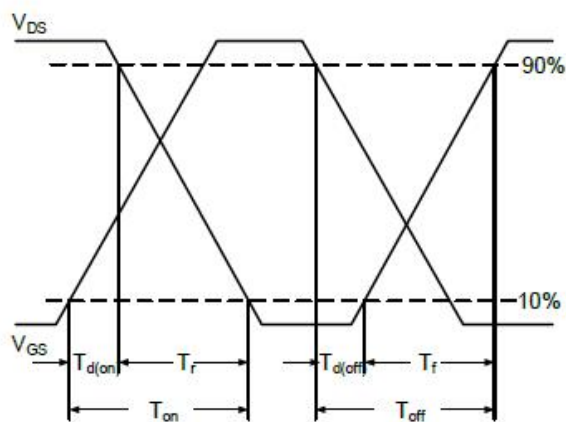
**Fig.7 Capacitance**



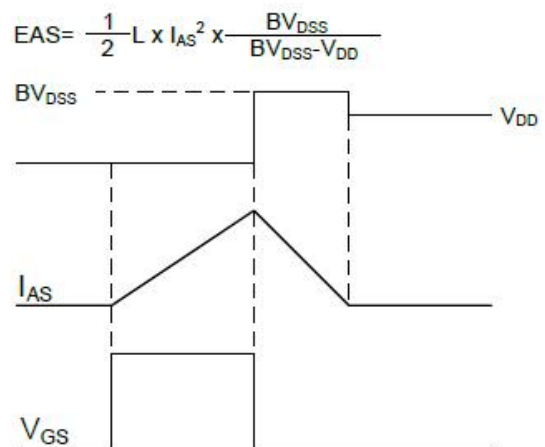
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Wave**